PCN 16\_0044 ADG201HS Conversion to 8-Inch Wafer Diameter for Aerospace Models

QUALIFICATION PLAN FOR AEROSPACE MODELS

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| **TEST** | **SPECIFICATION** | **SAMPLE SIZE** | **ESTIMATED COMPLETION DATE** |
| High Temperature Operating Life Test | MIL-STD-883Method 1005 | 45(0) | August, 2016 |

PREVIOUS QUALIFICATION TESTS COMPLETED FOR COMMERCIAL PRODUCT RELEASE
(REF. PCN 04\_0080)

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| **TEST** | **SPECIFICATION** | **SAMPLE SIZE** | **RESULTS** |
| Early Life Failure Rate | JESD22-A108 | 3 lots X 300 pieces | Pass |
| High Temperature Operating Life Test | MIL-STD-883Method 1005 | 3 lots X 45 pieces | Pass |
| High Temperature Storage | JESD22-A1031000 Hrs @ +150C | 3 lots X 45 pieces | Pass |
| Temperature Cycle 1/ | MIL-STD-883TM1010500 Cycles-65 to +150C | 3 lots X 45 pieces | Pass |

1. Noted samples were subjected to preconditioning (per J-STD-020B Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following:
* Bake: 24 hrs @ 125°C
* Unbiased Soak: 192 hrs @ 30°C, 60%RH
* Reflow: 3 passes through a convection/IR oven with a peak temperature of 240 +0/-5°C for a minimum of 10 seconds.